



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2023-10-30
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	giovanni giacopello	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
VNF9Q20FTR	B140°XV1FABH	A	997G	2023-10-30
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	150.00	mg	Each	ECOPACK® 2
Identity	Authority			
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM01017642	
Package designator	Package size	Number of instances	Shape	
QFN	6.00x6.00x1.00	32	No lead	
Comment	VFQFPN 6X6X1 32 MIXPLANT RINGCUT			



QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 25th Feb 2022			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.050	die	333

QueryList : REACH-14th June 2023				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material

QueryList : Responsible metals sourcing		Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.		true
The following metals are present is the component :		<b>Tin, Tungsten,</b>

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update		Response
The Product does contain at least one of the substances listed in Chemical Control Act		false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020		Response
The product contains adhesives identified under GB 33372		false

Stockholm Convention Persistent Organic Pollutants		Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I		true

QueryList : EUSRR Directive		Response
Product contains hazardous materials listed in EUSRR Annex II		False

PFAS/PTFE Restriction		Response
Product contains Per- and Polyfluorinated Substance		False

BPA Restriction		Response
Product contains Bisphenol A (Isopropylidenediphenol)		False



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B140* XV1FABH									
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	4.134	mg	supplier	die	Silicon(Si)	7440-21-3		3.331	mg	805756	22208				
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.140	mg	33866	933				
				supplier	metallisation	Copper(Cu)	7440-50-8		0.058	mg	14030	387				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.050	mg	12095	333				
				supplier	metallisation	Silver(Ag)	7440-22-4		0.020	mg	4838	133				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.018	mg	4354	120				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.251	mg	60716	1673				
				supplier	metallisation	Vanadium(V)	7440-62-2		0.004	mg	968	27				
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.024	mg	5806	160				
				supplier	passivation	Silicon oxide	7631-86-9		0.134	mg	32414	893				
				supplier	polymer coating	polyimide	proprietary		0.104	mg	25157	693				
				Leadframe	M-004 Copper and its alloys	43.020	mg	supplier	alloy	Copper(Cu)	7440-50-8		40.698	mg	946025	271320
								supplier	alloy	Iron (Fe)	7439-89-6		0.716	mg	16643	4773
supplier	alloy	Iron phosphide	26508-33-8						0.167	mg	3882	1113				
supplier	alloy	Zinc(Zn)	7440-66-6						0.053	mg	1232	353				
supplier	metallization	Silver (Ag)	7440-22-4						1.386	mg	32218	9240				
supplier	wire	Copper(Cu)	7440-50-8						0.573	mg	1000000	3820				
Bonding wires	M-004 Copper and its alloys	0.573	mg	supplier	wire	Copper(Cu)	7440-50-8		0.493	mg	1000000	3287				
Bonding wires 2	M-004 Copper and its alloys	0.493	mg	supplier	wire	Copper(Cu)	7440-50-8		0.493	mg	1000000	3287				
Encapsulation	M-011 Other inorganic materials	101.765	mg	supplier	mold compound	Silica vitreous	60676-86-0		89.553	mg	879997	597020				
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		5.088	mg	49998	33920				
				supplier	mold compound	Phenolic resin	205830-20-2		3.969	mg	39002	26460				
				supplier	mold compound	Epoxy type resin	25068-38-6		2.035	mg	19997	13567				
				supplier	mold compound	Carbon black	1333-86-4		0.204	mg	2005	1360				
supplier	mold compound	other	proprietary		0.916	mg	9001	6107								
Connections coating	Solder	0.015	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.015	mg	1000000	100				